



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSOP-5/6

Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
85/85	275	44,880	85°C, 85%RH	0	0.00
BOND INT	805	463,820	200°C +N2	0	0.00
HAST	3,594	377,800	130°C, 85%RH	0	0.00
Pressure Pot	8,144	841,304	121°, 15 PSIG	0	0.00
Solder DUNK	1,437	4,671	260°C, 10SEC	0	0.00
Solderability	885	8,040	883 M2003	0	0.00
Temp Cycle	8,970	4,177,750	-65°C-150°C	0	0.00